

### 1. 封裝 Package

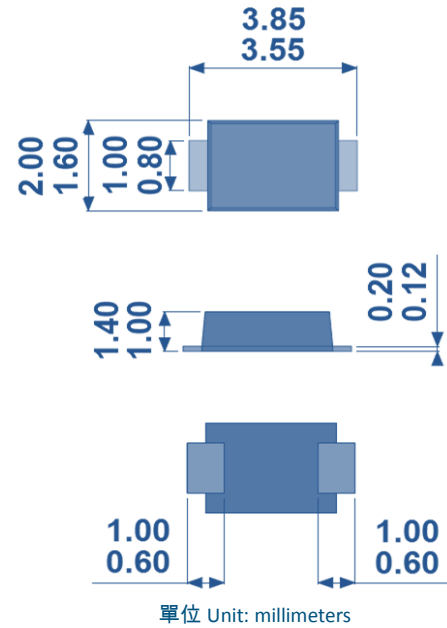
- 封裝方式 Method: SOD-123S
- 封裝尺寸 Dimension: 如圖示

### 2. 產品特色 Features

- For surface mounted applications
- Low profile package
- Ideal for automated placement
- High temperature soldering : 260°C/10 seconds at terminals
- Glass passivated chip junction
- Lead-free & halogen-free parts, RoHS compliant

### 3. 機械數據 Mechanical Data

- Epoxy: UL94V-0 rated flame retardant
- Case: Molded Plastic
- Terminals: Solder plated solderable per MIL-STD-750 Method 2026
- Mounting position: Any
- Polarity: Color band denotes cathode end
- Weight: approx.. 0.0173 grams



### 4. 極限值與電參數 Maximum Ratings & Electrical Characteristic

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	Symbol	GS1000FL	GS1001FL	GS1002FL	GS1004FL	GS1006FL	GS1008FL	GS1010FL	UNITS
Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	Volts
RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	Volts
DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	Volts
Average Forward Current (Note 1)	$I_{F(AV)}$	1.0							Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load(JEDEC Method)	$I_{FSM}$	30.0							Amps
Max. Forward Voltage at 1.0A	$V_F$	1.0							Volts
Max. DC Reverse Current $T_J=25^\circ\text{C}$ Rated DC Blocking Voltage	$I_R$	1							$\mu\text{A}$
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	65							$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-50 ~ +150							$^\circ\text{C}$

#### Notes:

- (1) Pulse test: 300u pulse with, 1% duty cycle.
- (2) Soldering land: 6mm x 6mm.

5. 特性曲線 Rating & Characteristic Curves

Fig. 1 Forward Current Derating Curve

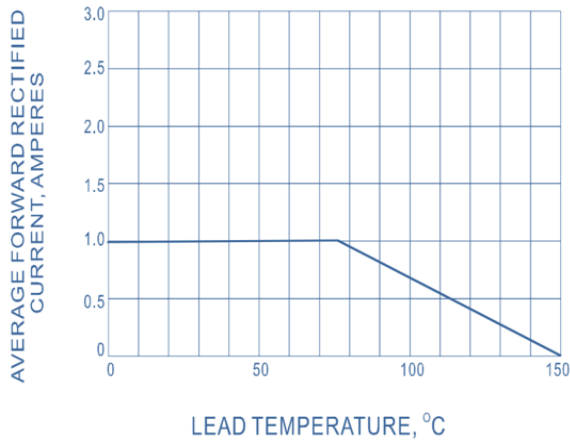


Fig. 2 Typical Instantaneous Forward Characteristics

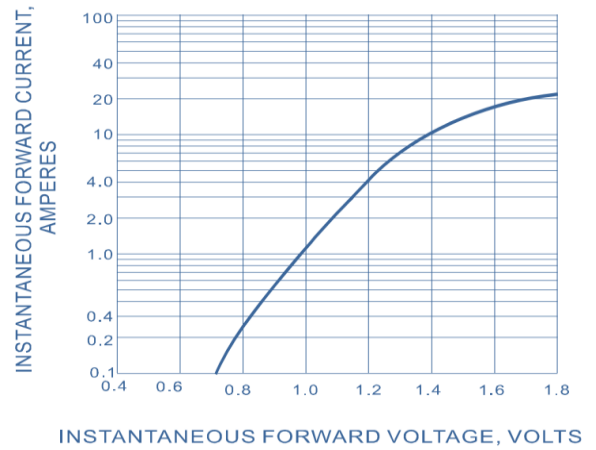


Fig. 3 Typical Reverse Characteristics

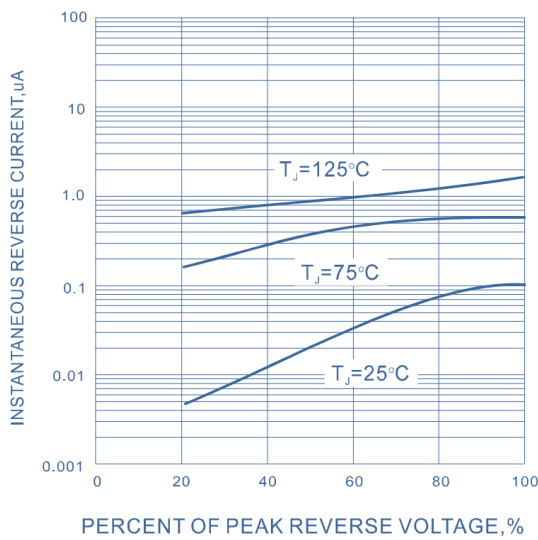


Fig. 4 Max. Non-Repetitive Surge Current

